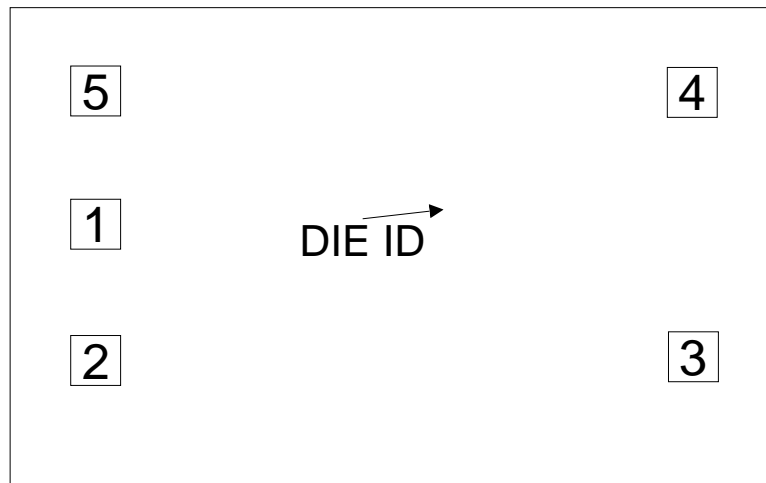


LM6211 MDC
LOW NOISE, RRO OP AMP WITH CMOS INPUT AND 24V OPERATION

November 19, 2009

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM6211B	Bond Pad Opening Size (min)	70.00µm x 70.00µm
Die Step	B	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	670.56µm x 1076.96µm 26.4mils x 42.4mils	Back Side Connection	V-
Thickness	254µm Nominal		
Min Pitch	186.90µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

This is a test of the Special Assembly Requirements text box.

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Die Bond Pad Coordinate Locations(B-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	Y
VOUT	1	-419	32	70	x	70
V+	2	-419	-160	70	x	70
IN -	3	420	-154	70	x	70
IN+	4	418	216	70	x	70
V -	5	-419	218	70	x	70

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